

Title (en)

BONDING METHOD FOR REDUCING STRESS IN MULTILAYERED WAFER

Title (de)

HAFTVERFAHREN ZUR REDUZIERUNG VON SPANNUNG IN MEHRLAGIGEM WAFER

Title (fr)

SYSTEME DE LIAISON A MAITRISE DES CONTRAINTES SYSTEME DE LIAISON A MAITRISE DES CONTRAINTESv

Publication

EP 1833754 A2 20070919 (EN)

Application

EP 05855006 A 20051221

Priority

- US 2005046376 W 20051221
- US 3127605 A 20050107

Abstract (en)

[origin: WO2006073829A2] An approach where items of different temperatures are bonded to each other such that upon cooling down they contract in size resulting in zero residual stress between the bonded items at an ambient temperature. If materials of the bonded items have different thermal expansion coefficients and the items are put together at different bonding temperatures, then they may have insignificant residual stress upon cooling down to the ambient temperature (e.g., room temperature) because the different ranges of the temperature drops compensate for the different contractions.

IPC 8 full level

B81C 3/00 (2006.01); **B81C 99/00** (2010.01)

CPC (source: EP US)

B81C 3/001 (2013.01 - EP US); **H01L 21/185** (2013.01 - EP); **B81C 2203/031** (2013.01 - EP US)

Citation (search report)

See references of WO 2006073829A2

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 2006073829 A2 20060713; **WO 2006073829 A3 20060824**; EP 1833754 A2 20070919; JP 2008526537 A 20080724; US 2006154443 A1 20060713; US 7691723 B2 20100406

DOCDB simple family (application)

US 2005046376 W 20051221; EP 05855006 A 20051221; JP 2007550390 A 20051221; US 3127605 A 20050107